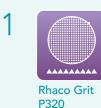
Aka-Brief #1 Copper and Copper Alloys















Times are stated for a 300 mm preparation system and Forces for an individual 40 mm dia. sample.

On a 250 mm system the times should be increased by 30%, on a 200 mm system by 100%.

BF, 100x

BF, 100x

BF, 100x

BF, 100x

With larger samples the force should be increased, with smaller samples decreased.

The rotational speed of the head (sample holder or sample mover plate) used is 150 rpm.

Time and Force may vary depending on the equipment.

* Prior to oxide polishing the polishing cloth should be wetted with water until the holder touches the polishing cloth. For the last 10 seconds of the oxide polishing step, the polishing cloth should be flushed with water to clean both sample(s) and polishing cloth.

** 96 ml Fumed Silica. 2 ml H₂O₂ (30%), 2 ml NH₄OH (25%).

The mixture should be used fresh (within a couple of hours) and stirred regularly.





300 rpm

25 N













DiaUltra

150 rpm



25 N

30 N













Chemal*



0.2 µm

Alkaline**

DiaUltra

3 µm

Fumed Silica 150 rpm













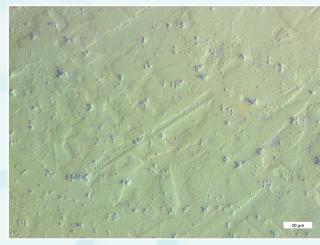


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FINAL RESULT





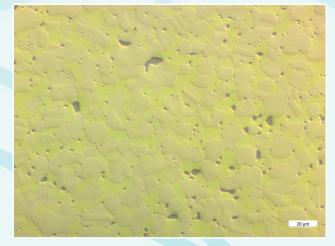


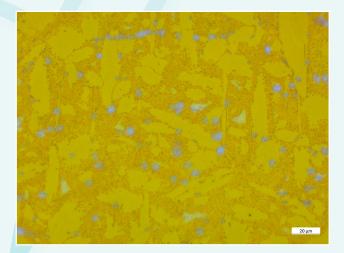
Copper, DIC, 100x

Brass, DIC, 200x

Bronze, DIC, 500x







Copper, DIC, 200x

Brass, DIC, 500x

Bronze, etched with Cu m7 (Petzow), BF, 500x

